Freeform Search

Database: US Pre-Grant Publication Full-Text Database
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IBM Technical Disclosure Bulletins

Term: L56 and (thermometer or probe)

Display: 10 Documents in Display Format: - Starting with Number 1

Generate: ○ Hit List ◉ Hit Count ○ Side by Side ○ Image

Search Clear Interrupt

Search History

DATE: Tuesday, March 15, 2005 Printable Copy Create Case

Set Name side by side	Query	Hit Count	Set Name result set
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L57	L56 and (thermometer or probe)	144	L57
L56	L55 and (circuit or board or electronics)	354	L56
L55	L10 and "thermal insulation"	545	L55
L54	L10 and "thermally insulated cavity"	0	L54
DB=USPT; PLUR=YES; OP=ADJ			
L53	L52 and "glue"	1	L53
L52	5109864.pn.	1	L52
L51	L50 and (insulat$3)	0	L51
L50	5782561.pn.	1	L50
L49	L48 and (insulat$3)	0	L49
L48	5743647.pn.	1	L48
DB=PGPB; PLUR=YES; OP=ADJ			
L47	L46 and "5"	1	L47
L46	20030169803	1	L46
L45	L44 and "5"	1	L45

L44	20040169803	1	L44
DB=USPT; PLUR=YES; OP=ADJ			
L43	L41 and "curcuit"	0	L43
L42	L41 and (insulat$3)	0	L42
L41	3903744.pn.	1	L41
L40	5420757.pn.	1	L40
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L39	(microprocessor chip) same (epoxy)	19	L39
L38	(microprocessor package) same (epoxy)	5	L38
L37	insulat$3 embed$2 processor	0	L37
L36	encapsulat$3 processor	38	L36
L35	processor encapsulat3 epoxy	0	L35
L34	processor embed$3 epoxy	1	L34
L33	microprocessor encapsulat$3 epoxy	0	L33
L32	circuit encapsulat$3 epoxy	18	L32
L31	circuit embedded epoxy	2	L31
L30	microprocessor embedded epoxy or microprocessor encapsulated epoxy	0	L30
L29	epoxy housing	124	L29
L28	L10 and "epoxy housing"	2	L28
L27	L24 and "epoxy housing"	0	L27
L26	L24 and (encapsulat$3 board or encapsulat$3 electronics)	4	L26
L25	L24 and (thermometer or temperature sens$3)	15	L25
L24	insulat$3 circuit board or insulat$3 printed boardor insulat$3 microprocessor	709	L24
L23	(circuit or microprocessor) same (epoxy insulat$3)	229	L23
L22	L10 and (epoxy insulat$3)	9	L22
L21	L10 and (low thermal conductI$5)	534	L21
L20	L10 and "plastic housing"	73	L20
L19	L10 and "data logger"	81	L19
L18	(data logger) same (thermal$2 insulat$3 housing)	0	L18
L17	L10 and (thermal$2 insulat$2 housing)	18	L17
L16	L1 and (thermal$2 insulat$3 housing)	0	L16
L15	L14 and (insulat$3 housing)	28	L15
L14	L10 and "digital"	4200	L14
L13	L12 and "digital"	49	L13
L12	L10 and (waterproof$2 housing or seal$3 housing)	145	L12
L11	L10 and "pacifier"	46	L11
L10	374/$	25902	L10
L9	L8 and "waterproof"	60	L9
L8	L7 and "thermometer"	5616	L8
L7	374/$	25902	L7
DB=PGPB,USPT,USOC,EPAB,JPAB; PLUR=YES; OP=ADJ			

L6	L5 and (waterproof or seal)	85	L6
L5	L4 and (cook$3 or food or meat or wine)	288	L5
L4	(374/208,159;116/216,200)[CCLS]	3076	L4
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L3	cooking thermometer	80	L3
DB=JPAB; PLUR=YES; OP=ADJ			
L2	01032131	1	L2
L1	10318542	1	L1

END OF SEARCH HISTORY

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Term: L26 and "0-ring"

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DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L28	L26 and "0-ring"	49	L28
L27	L26 and "gasket"	301	L27
L26	L1 and "screw"	3280	L26
DB=USPT; PLUR=YES; OP=ADJ			
L25	L23 and "screw"	0	L25
L24	L23 and "screw" and "gasket"	0	L24
L23	5005986.pn.	1	L23
L22	6367974.pn.	1	L22
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L21	heat resistant glue or thermally resistant glue	78	L21
L20	L1 and (thermal$2 resistant glue)	0	L20
L19	L1 and "heat resistant glue"	0	L19
L18	foam insulated housing	4	L18
L17	L1 and (insulat$3 foam)	28	L17
L16	L1 and "foam"	591	L16
DB=USPT; PLUR=YES; OP=ADJ			

L15	L12 and "foam"	58	L15
L14	L12 and "insulation foam"	1	L14
L13	L12 and "insulation"	248	L13
L12	374/208	1586	L12
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L11	5741072[uref]	2	L11
L10	L9 and (probe or thermometer)	197	L10
L9	L1 and "heat resistant"	475	L9
L8	L1 and "thermally insulated jacket"	0	L8
L7	L1 and (thermal$2 insulat$3)	1338	L7
L6	5100244[uref]	3	L6
L5	L1 and (thermally insulated enclosure or thermally insulated housing)	27	L5
L4	L3 and (thermometer or probe)	145	L4
L3	L2 and (circuit or board or electronics or processor)	364	L3
L2	L1 and "thermal insulation"	545	L2
L1	374/$	25902	L1

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Term: L32 and "threaded connection"

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DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L34	L32 and "threaded connection"	122	L34
L33	L31 and "threaded connection"	0	L33
L32	L1 and "threaded"	2837	L32
DB=USPT; PLUR=YES; OP=ADJ			
L31	L29 and "ring"	1	L31
L30	L29 and "screw"	0	L30
L29	6431110.pn.	1	L29
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L28	L26 and "0-ring"	49	L28
L27	L26 and "gasket"	301	L27
L26	L1 and "screw"	3280	L26
DB=USPT; PLUR=YES; OP=ADJ			
L25	L23 and "screw"	0	L25
L24	L23 and "screw" and "gasket"	0	L24
L23	5005986.pn.	1	L23
L22	6367974.pn.	1	L22

DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
L21	heat resistant glue or thermally resistant glue	78	L21
L20	L1 and (thermal$2 resistant glue)	0	L20
L19	L1 and "heat resistant glue"	0	L19
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L16	L1 and "foam"	591	L16
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L15	L12 and "foam"	58	L15
L14	L12 and "insulation foam"	1	L14
L13	L12 and "insulation"	248	L13
L12	374/208	1586	L12
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ			
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L10	L9 and (probe or thermometer)	197	L10
L9	L1 and "heat resistant"	475	L9
L8	L1 and "thermally insulated jacket"	0	L8
L7	L1 and (thermal$2 insulat$3)	1338	L7
L6	5100244[uref]	3	L6
L5	L1 and (thermally insulated enclosure or thermally insulated housing)	27	L5
L4	L3 and (thermometer or probe)	145	L4
L3	L2 and (circuit or board or electronics or processor)	364	L3
L2	L1 and "thermal insulation"	545	L2
L1	374/$	25902	L1

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L5	L4 and (cook$3 or food or meat or wine)	288	L5
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DB=JPAB; PLUR=YES; OP=ADJ			
L2	01032131	1	L2
L1	10318542	1	L1

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